United States Patent [19]
Du Bois

[11] **Patent Number: Des. 288,557**
[45] **Date of Patent: ** Mar. 3, 1987**

[54] **SEMICONDUCTOR HOUSING**

[75] Inventor: **Jerry M. Du Bois,** Mesa, Ariz.

[73] Assignee: **Motorola, Inc.,** Schaumburg, Ill.

[**] Term: **14 Years**

[21] Appl. No.: **649,081**

[22] Filed: **Sep. 10, 1984**
[52] **U.S. Cl.** **D13/99;** D13/41
[58] **Field of Search** .... D13/40, 41, 99; 361/394, 395, 399, 400, 331; 174/52 R, 52 PE, 52 S; 357/70, 72, 74

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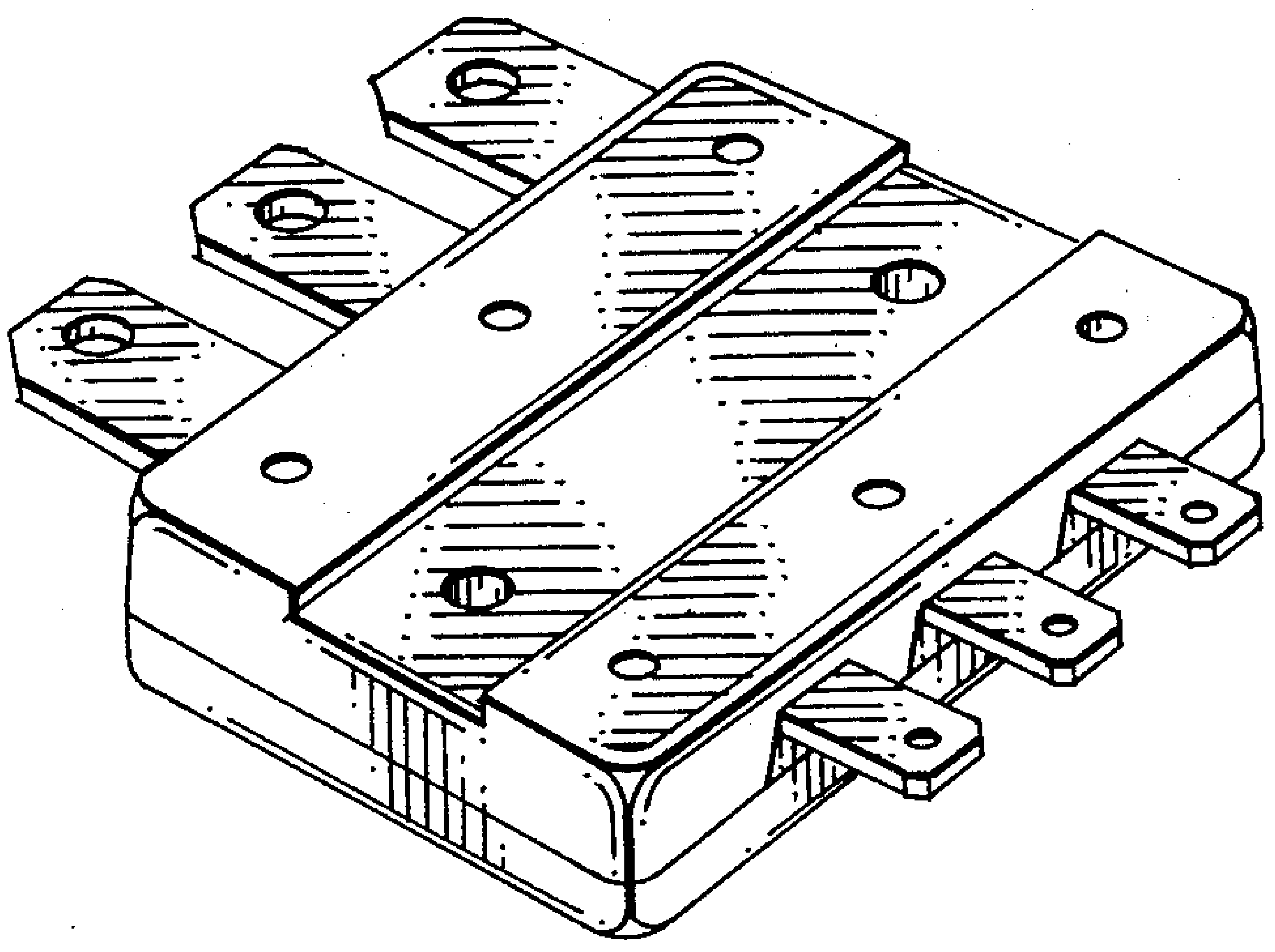
Primary Examiner—Susan J. Lucas
Attorney, Agent, or Firm—Robert Handy

[57] **CLAIM**

The ornamental design for a semiconductor housing, as shown and described.

DESCRIPTION

FIG. **1** is a right side, top and front perspective view of a semiconductor housing showing my new design;
FIG. **2** is a top plan view thereof on a reduced scale;
FIG. **3** is a bottom plan view thereof on a reduced scale;
FIG. **4** is a left side elevational view thereof on a reduced scale;
FIG. **5** is a right side elevational view thereof on a reduced scale;
FIG. **6** is a front elevational view thereof on a reduced scale;
FIG. **7** is a rear elevational view thereof on a reduced scale;
FIG. **8** is a top plan view of second embodiment of my new design, the second embodiment being identical to the first except for the number of leads on the right hand side;
FIG. **9** is a bottom plan view thereof;
FIG. **10** is a top plan view of a third embodiment of my new design, the third design being identical to the first embodiment except for the shape of the two leads on the left hand side;
FIG. **11** is a bottom plan view thereof;
FIG. **12** is a right side, top and front perspective view of a fourth embodiment of my new design;
FIG. **13** is a top plan view thereof on a reduced scale;
FIG. **14** is a front elevational view thereof on a reduced scale;
FIG. **15** is a left side elevational view thereof on a reduced scale;
FIG. **16** is a right side, top and front perspective view of a fifth embodiment of my new design, the fifth embodiment being identical to the first embodiment except for the flat top surface;
FIG. **17** is a right side, top and front perspective view of a sixth embodiment of my new design;
FIG. **18** is a top plan view thereof on a reduced scale;
FIG. **19** is a bottom plan view thereof on a reduced scale;
FIG. **20** is a left side elevational view thereof on a reduced scale;
FIG. **21** is a right side elevational view thereof on a reduced scale.



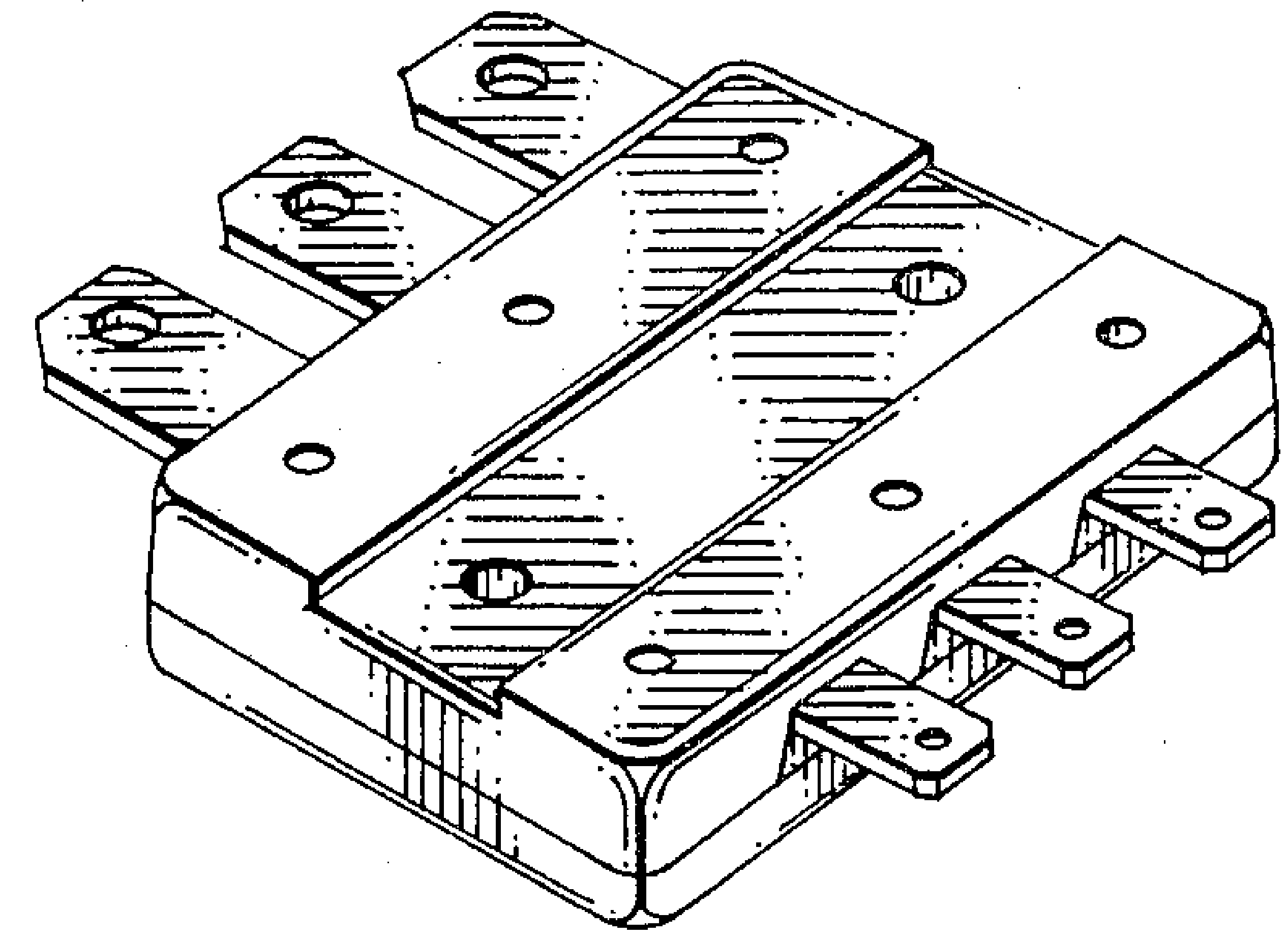


FIG. 1

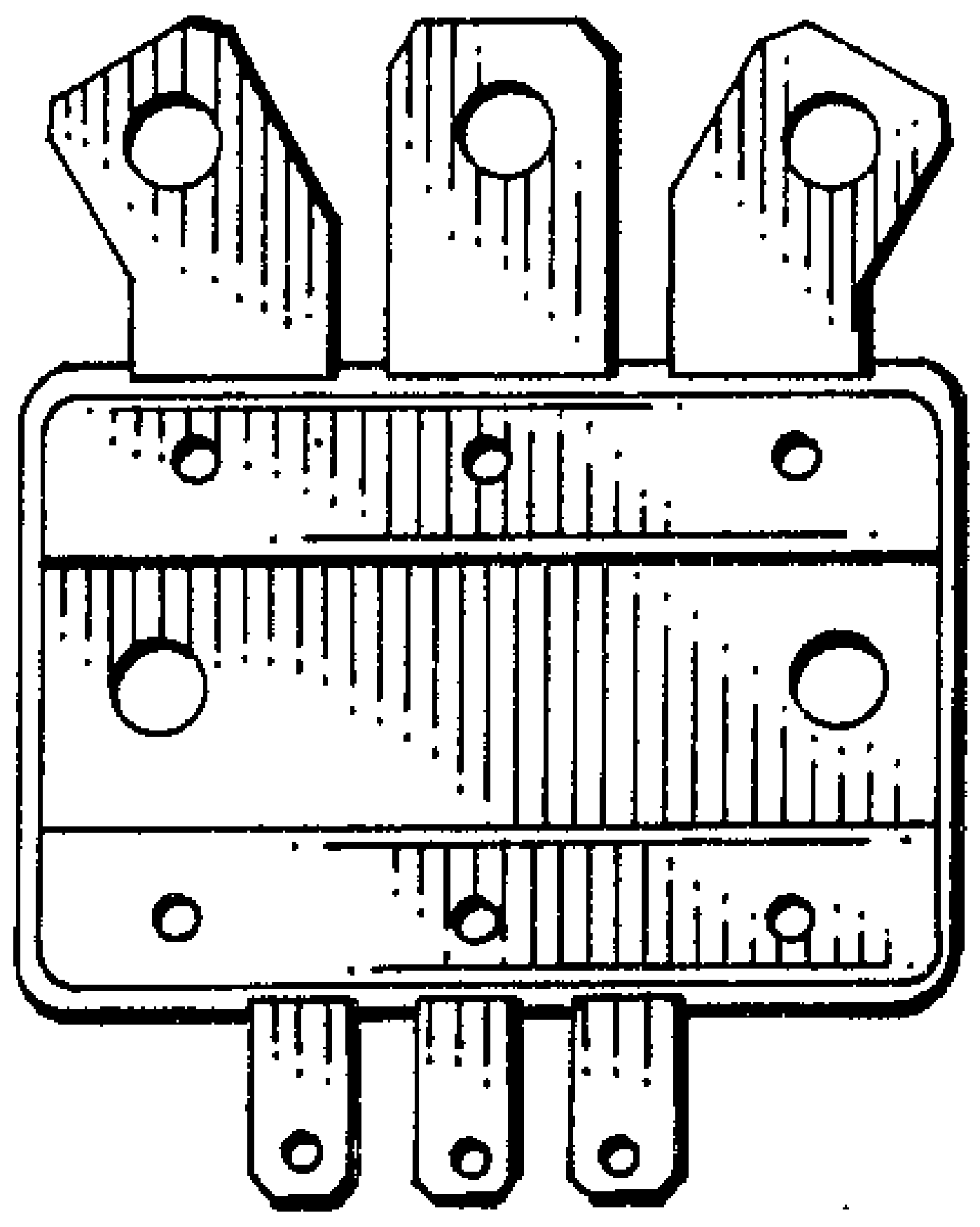


FIG. 10

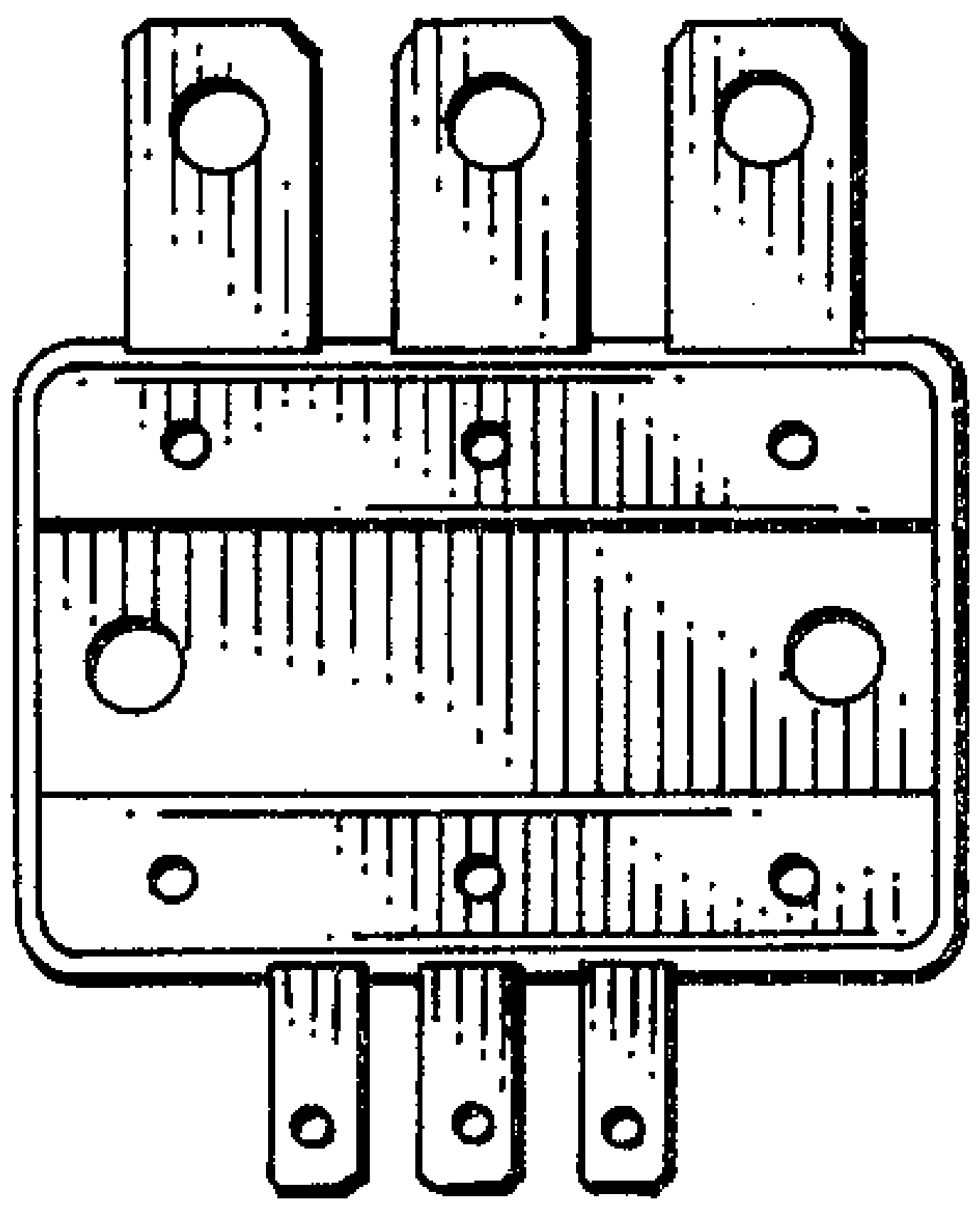


FIG. 2

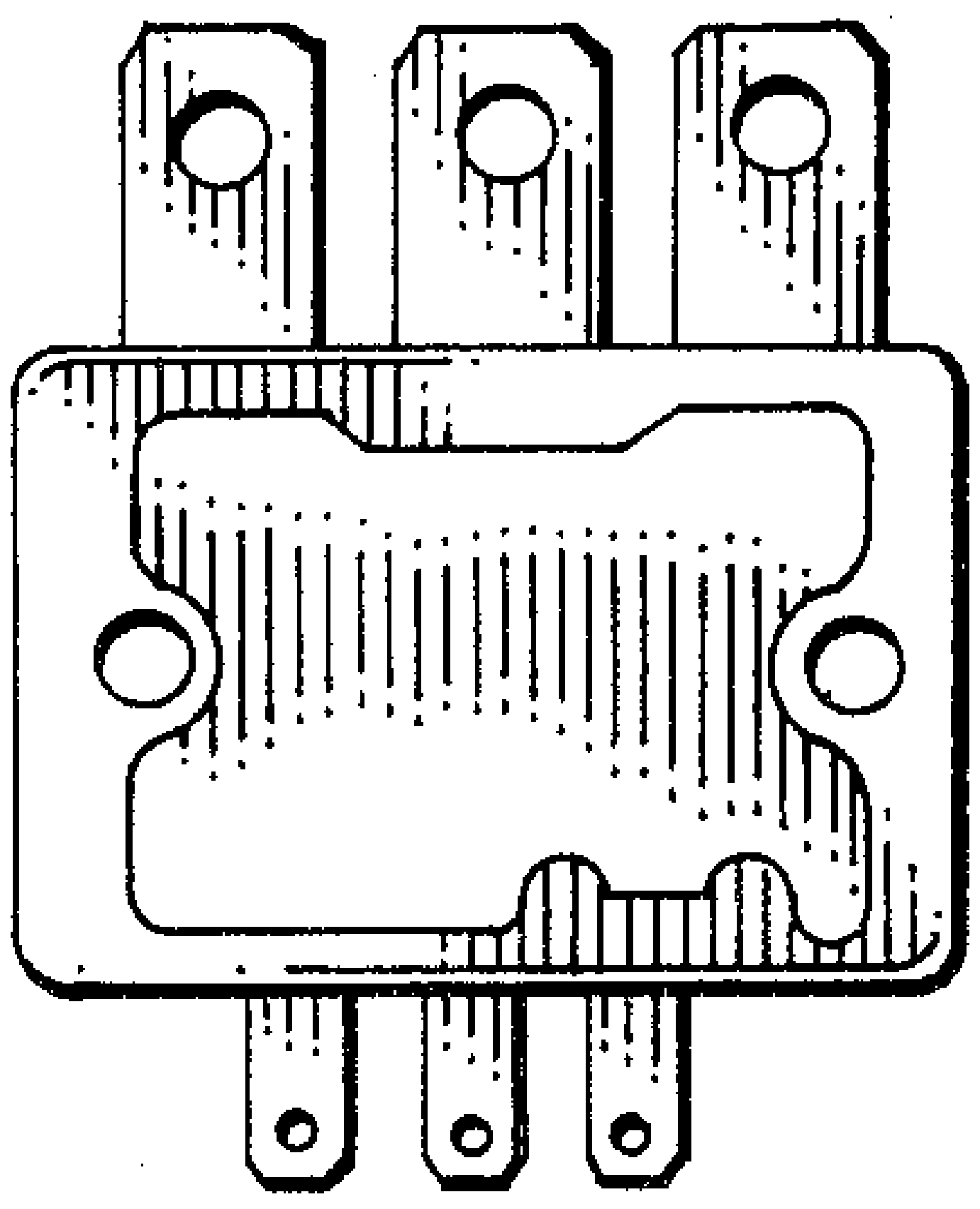


FIG. 3

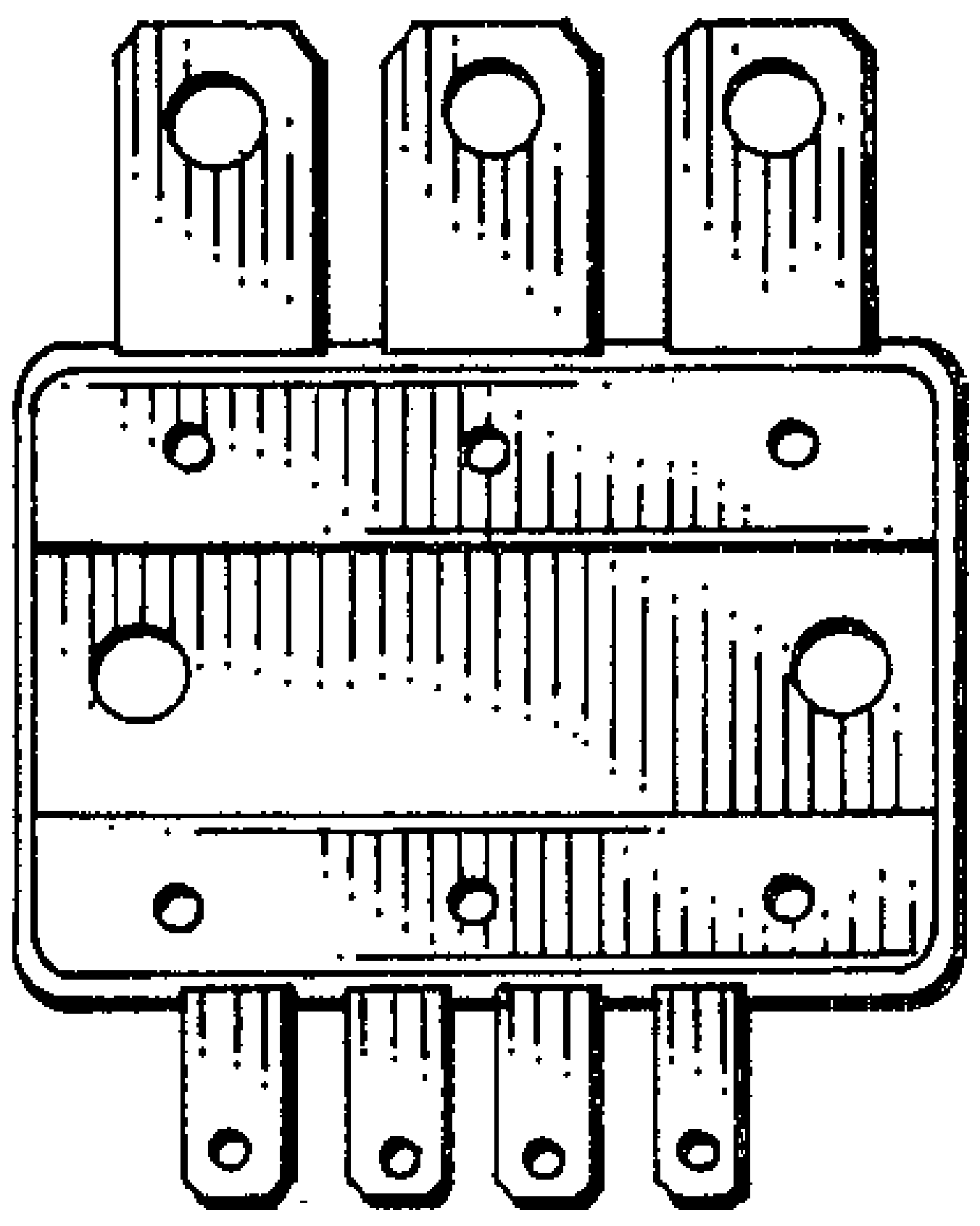


FIG. 8

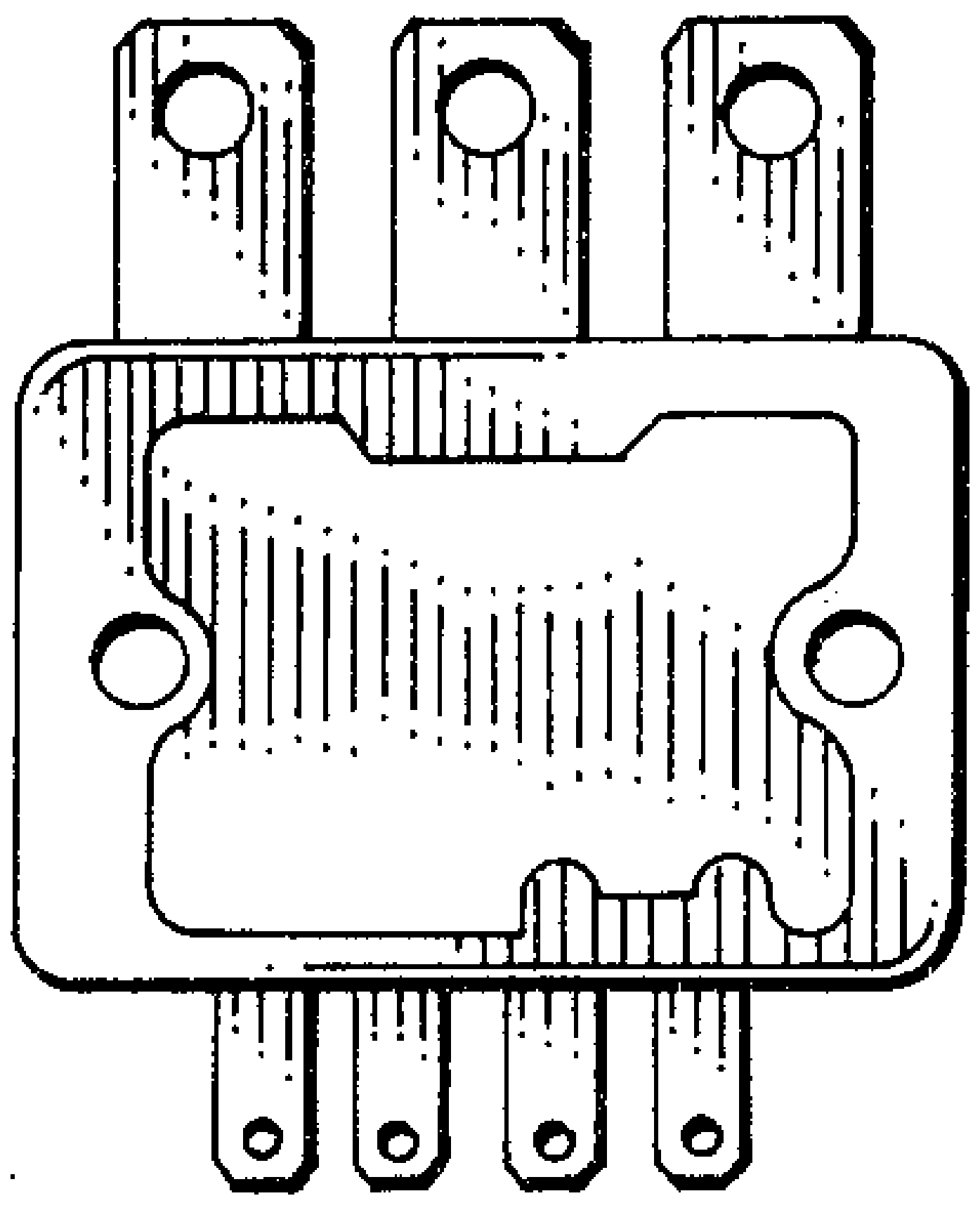


FIG. 9

FIG. 4

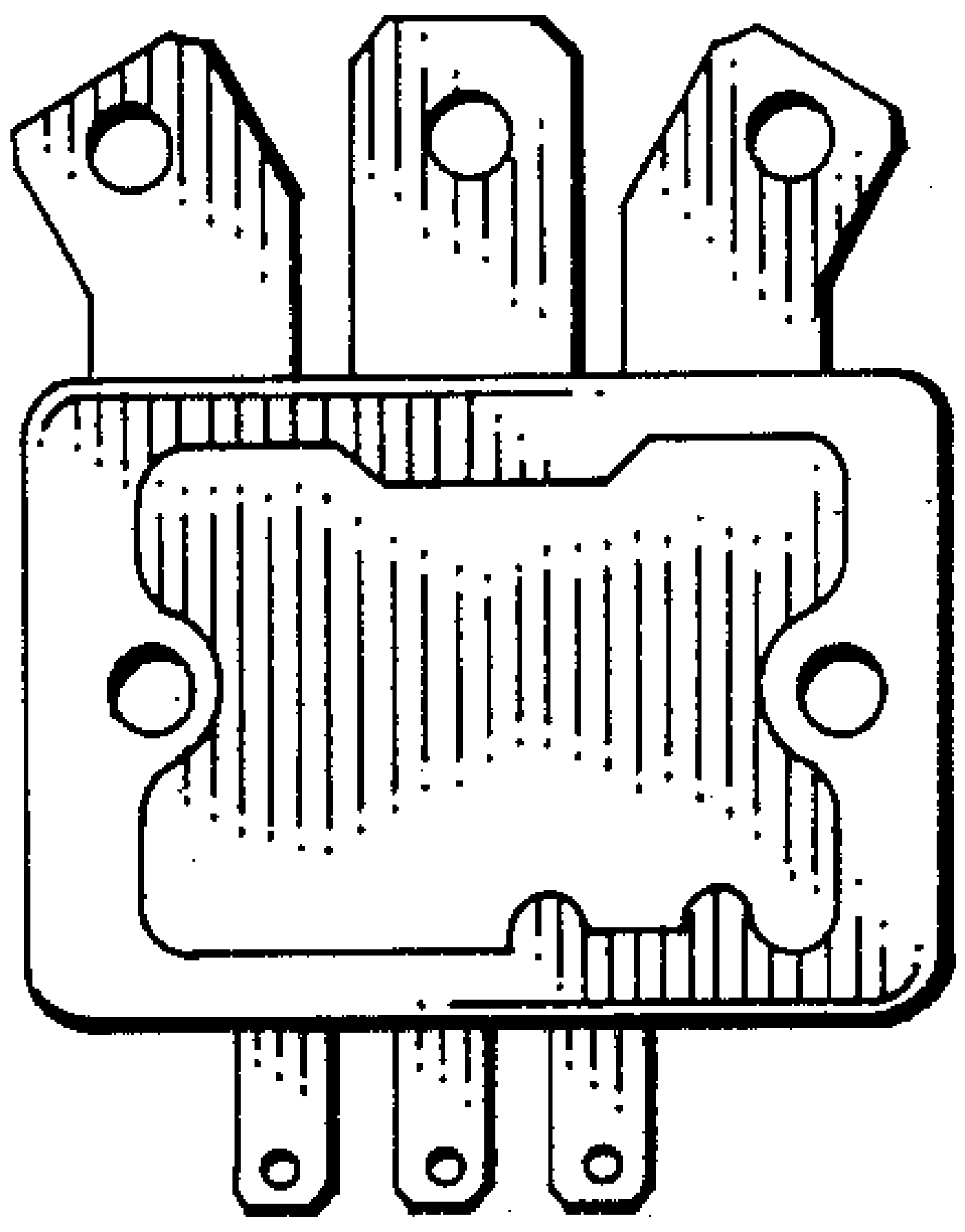


FIG. 11

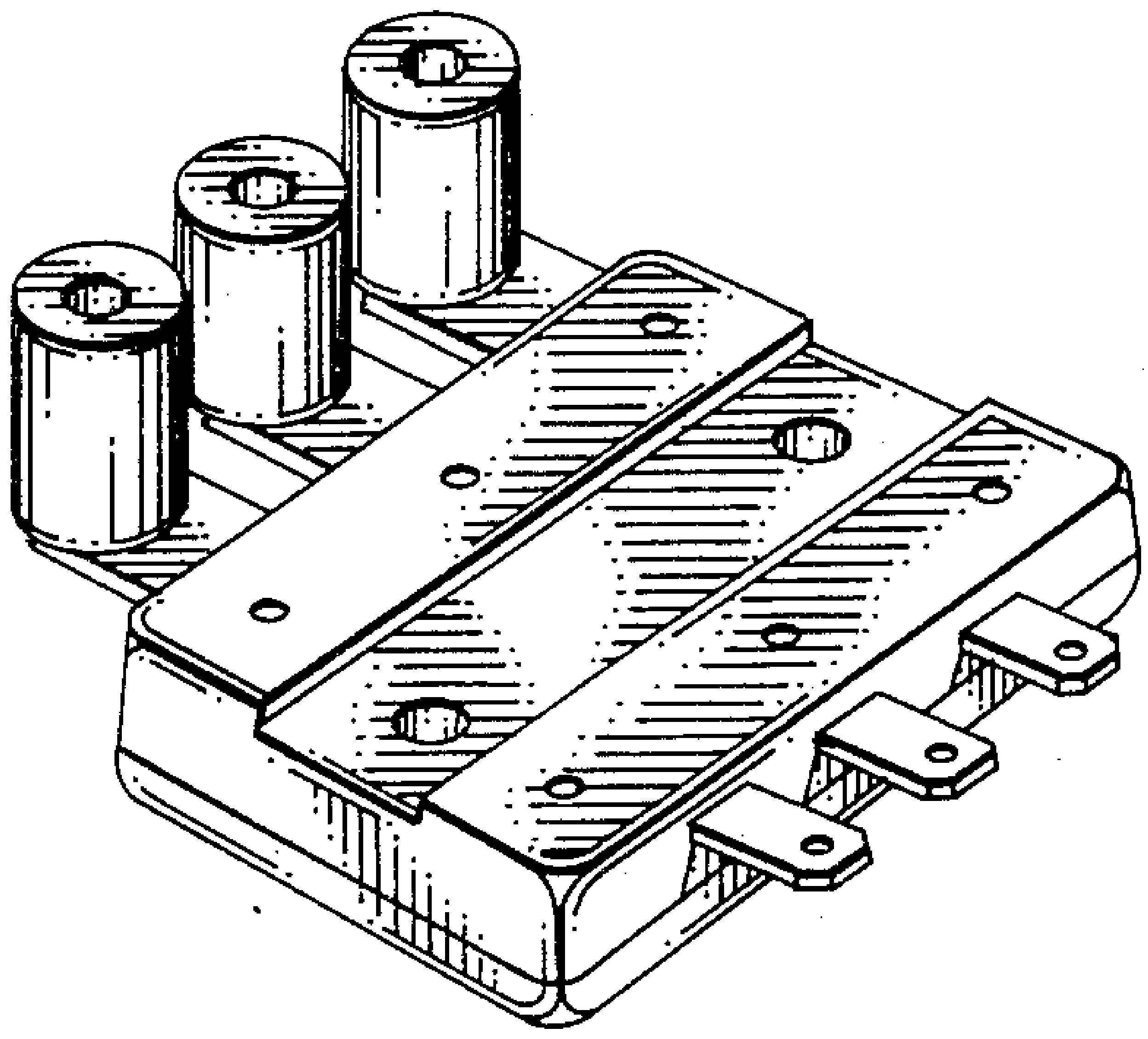


FIG. 12

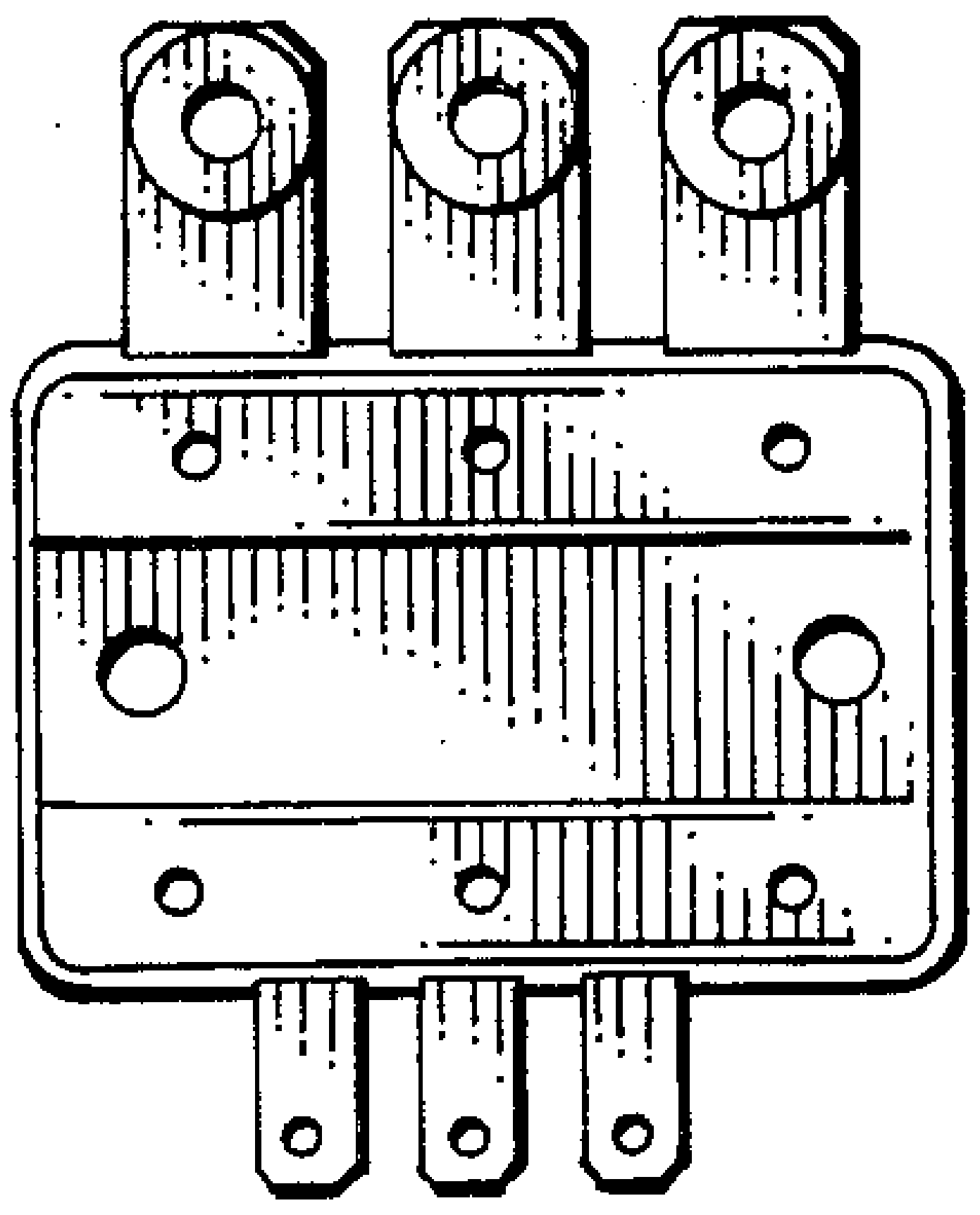


FIG. 13

FIG. 5

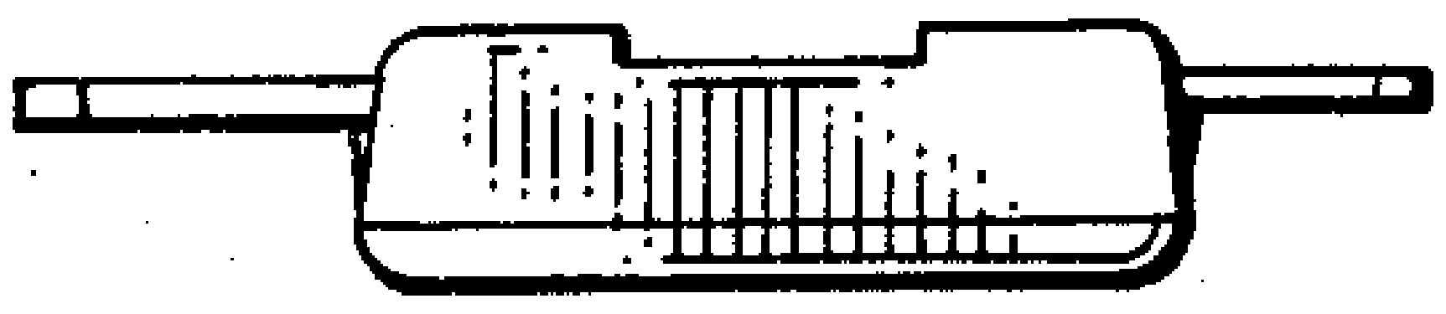


FIG. 6

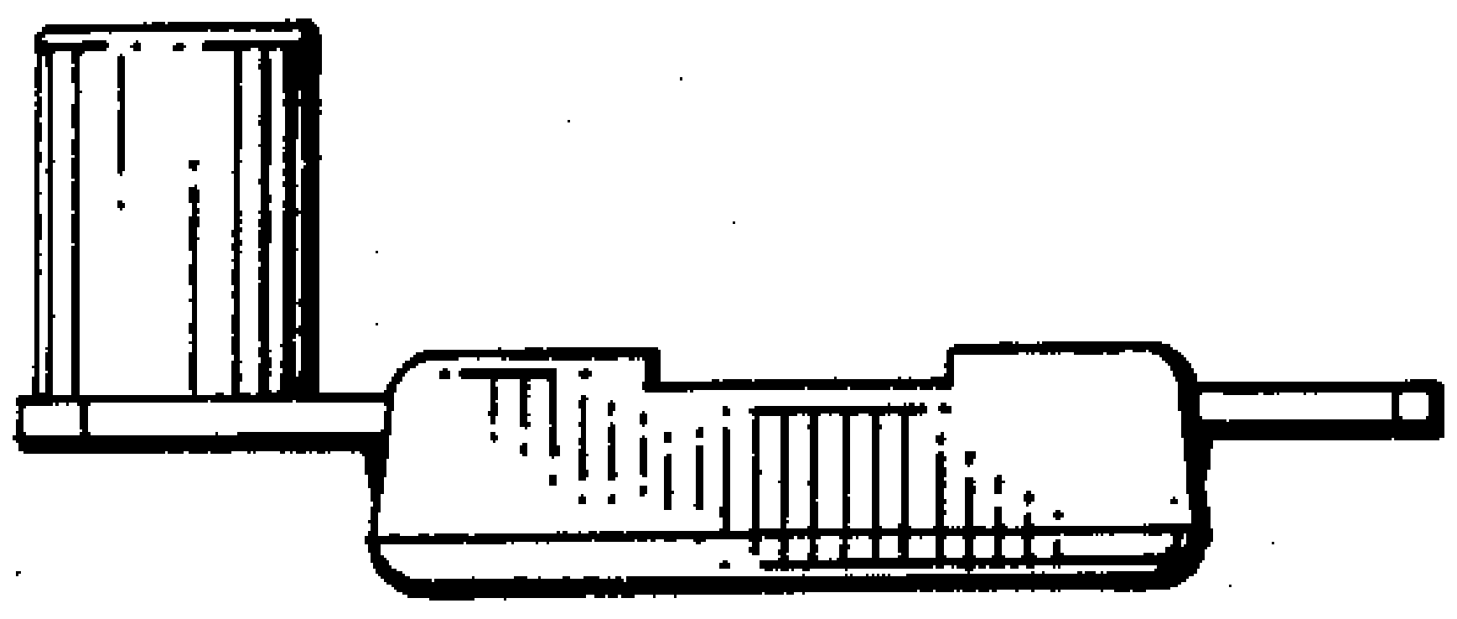


FIG. 14

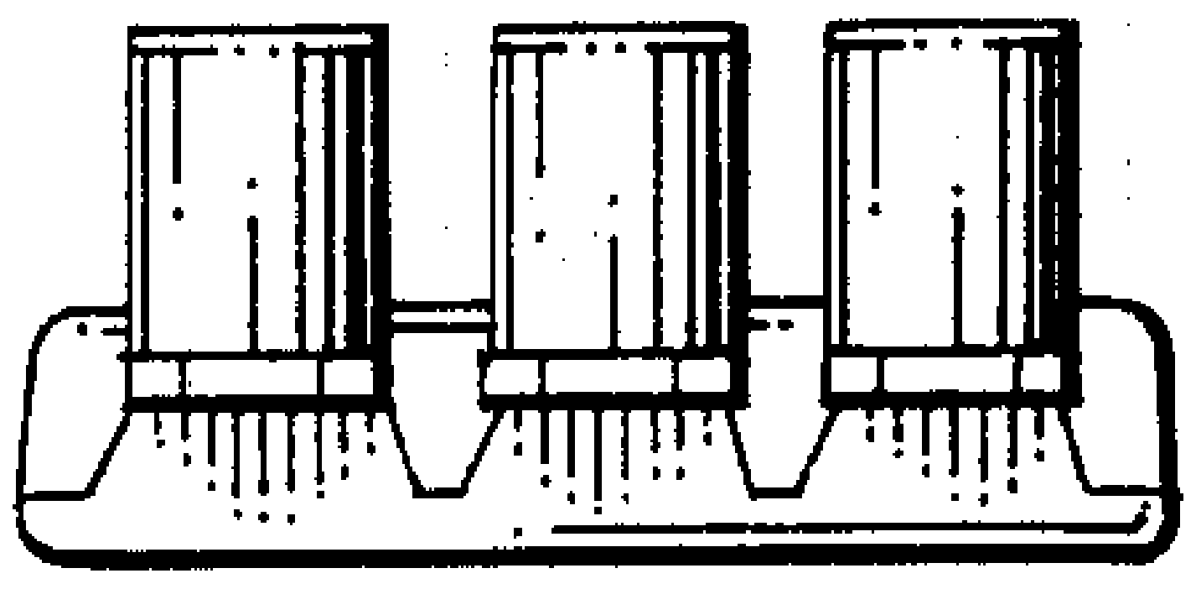


FIG. 15

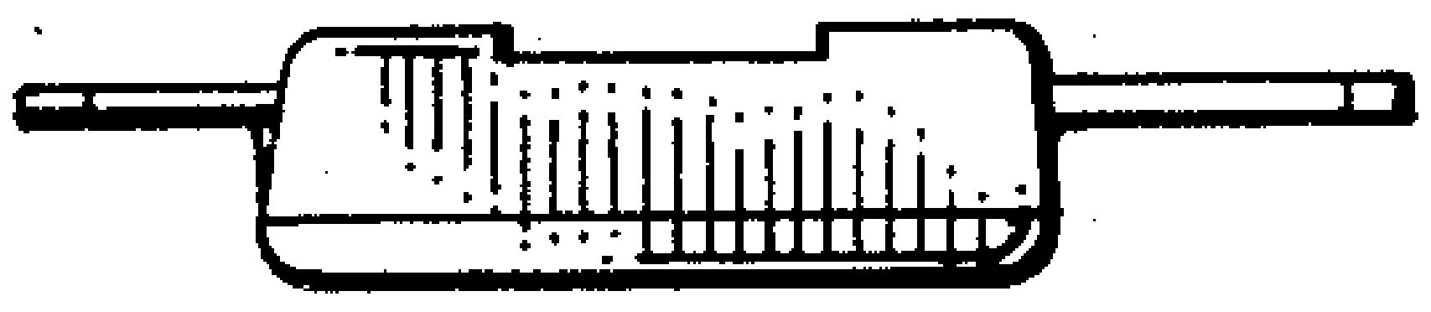


FIG. 7

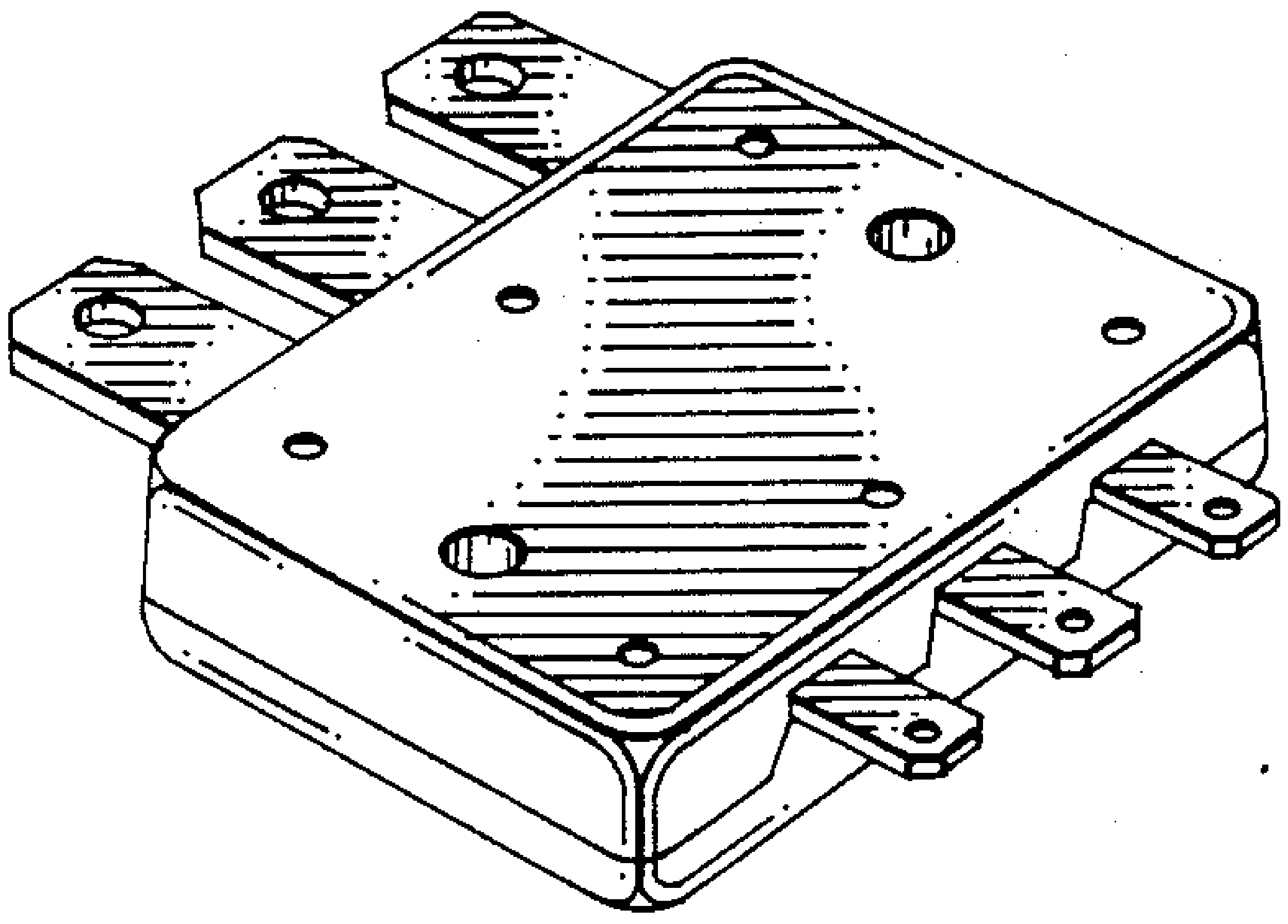


FIG. 16

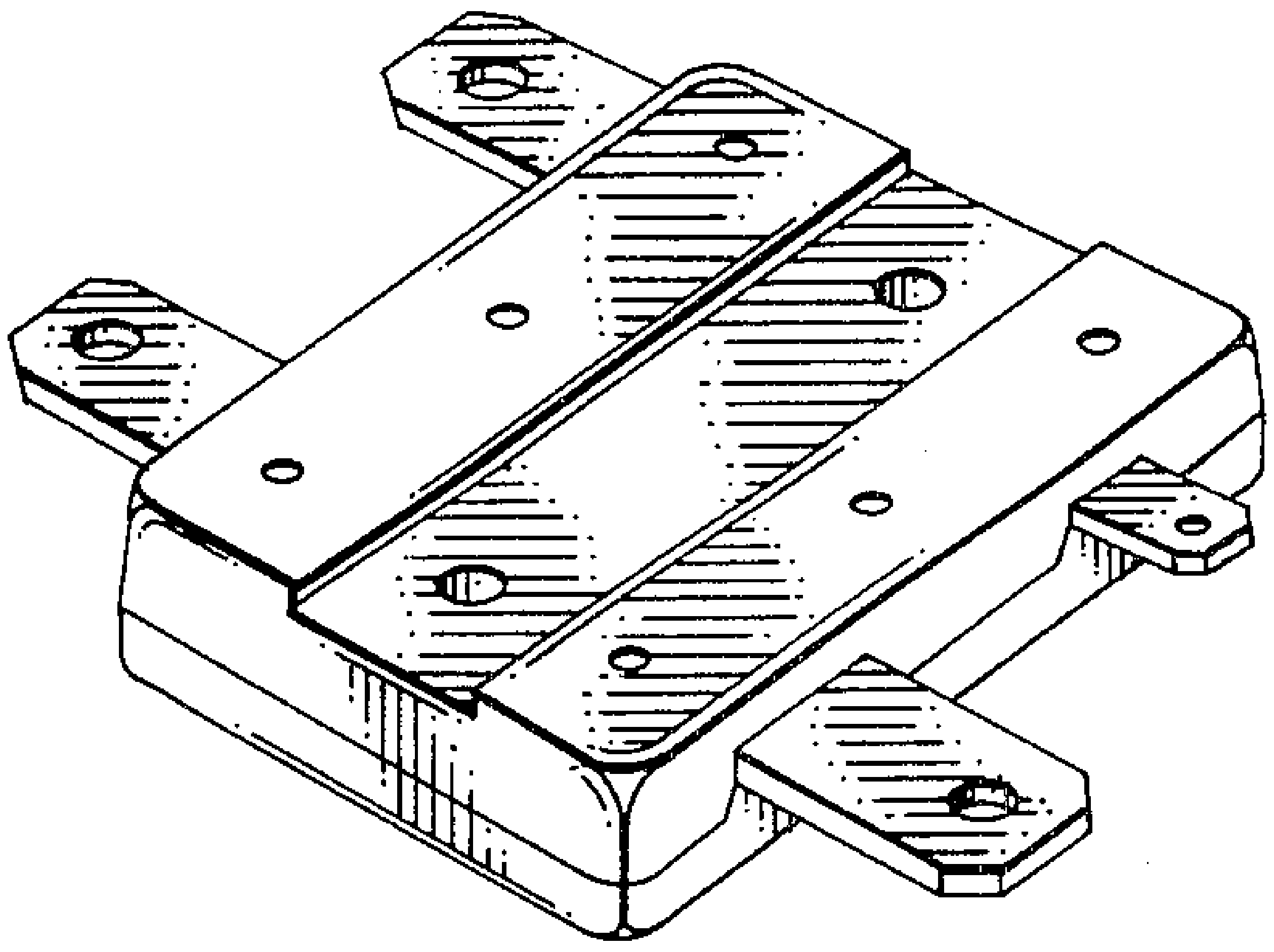


FIG. 17

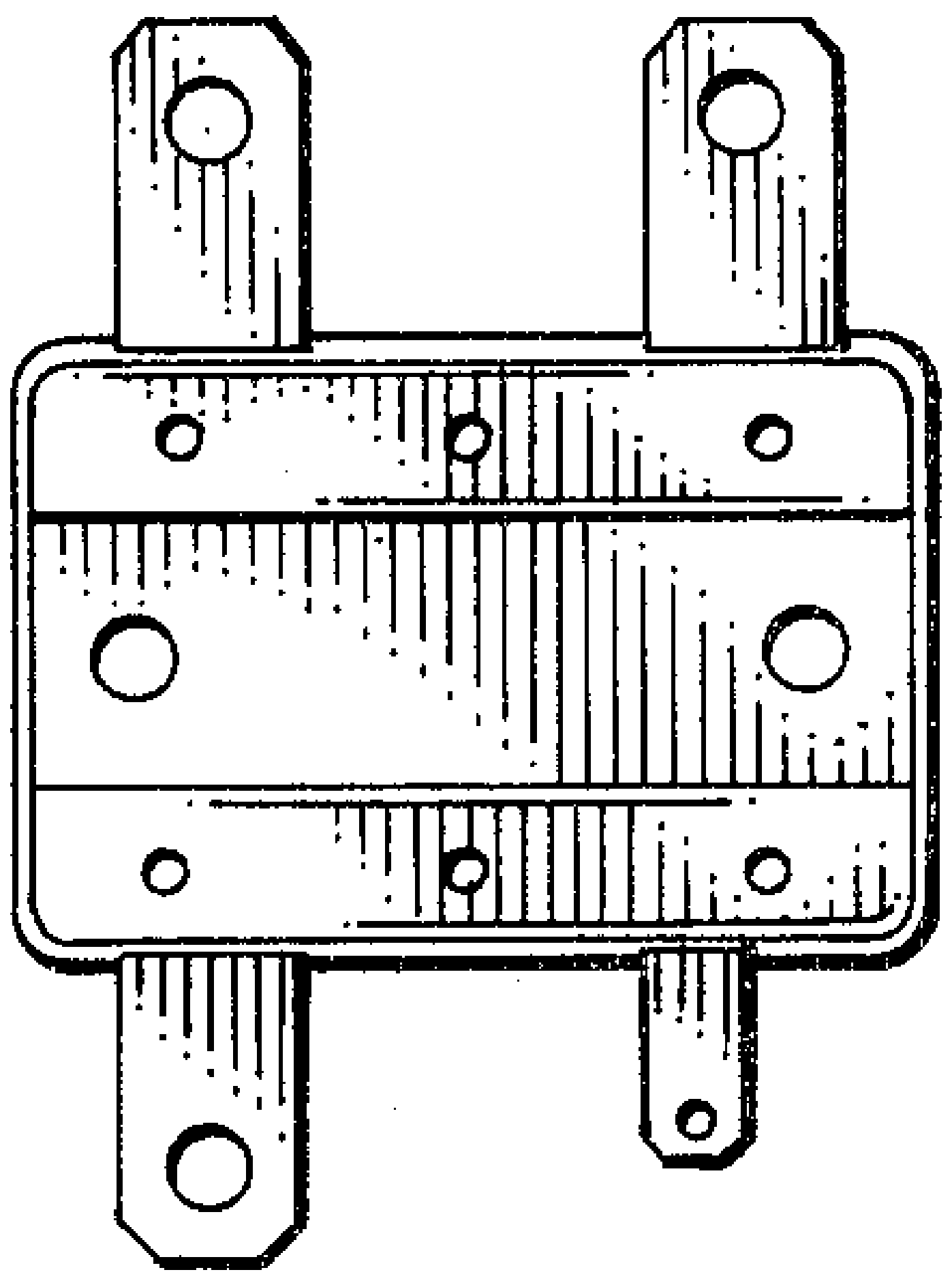


FIG. 18

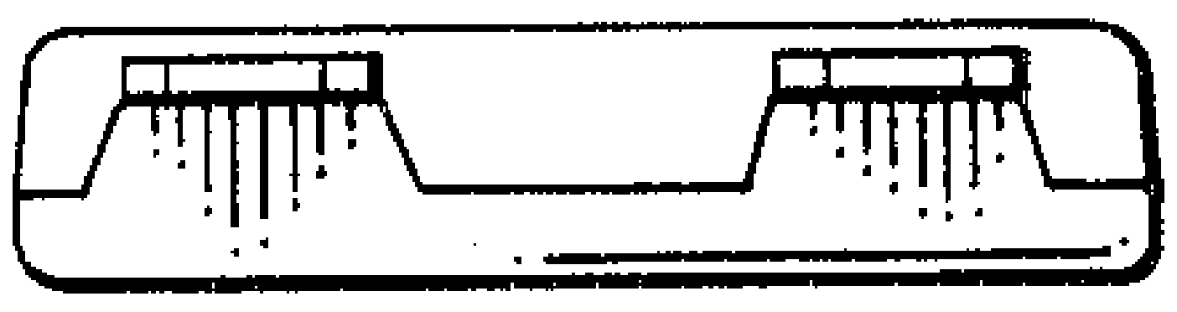


FIG. 20

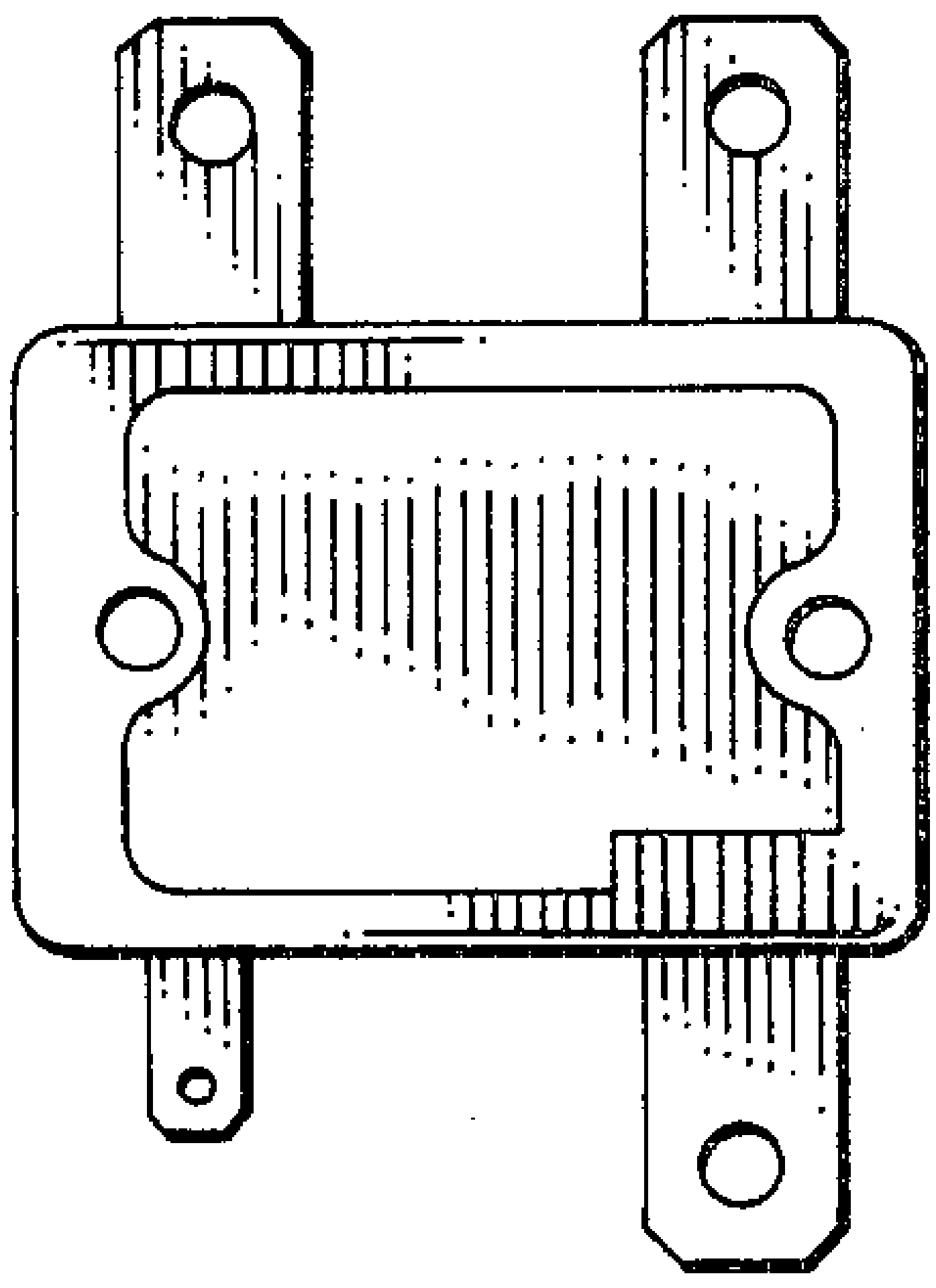


FIG. 19

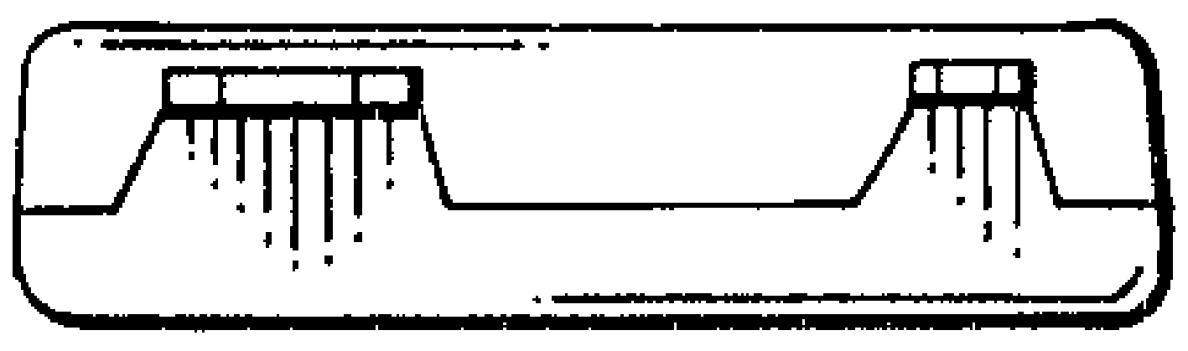


FIG. 21